

Switch Mode Power Rectifiers

MBR8H100MFS, NRVB8H100MFS

Features

- Low Power Loss / High Efficiency
- New Package Provides Capability of Inspection and Probe After Board Mounting
- Guardring for Stress Protection
- Low Forward Voltage Drop
- 175°C Operating Junction Temperature
- WF Suffix for Products with Wetttable Flanks
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free Devices

Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94-0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements

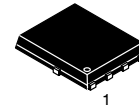
MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|---------------------------------|-------------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 100 | V |
| Average Rectified Forward Current (Rated V_R , $T_C = 165^\circ\text{C}$) | $I_{F(AV)}$ | 8.0 | A |
| Peak Repetitive Forward Current, (Rated V_R , Square Wave, 20 kHz, $T_C = 162^\circ\text{C}$) | I_{FRM} | 16 | A |
| Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | I_{FSM} | 75 | A |
| Storage Temperature Range | T_{stg} | -65 to +175 | °C |
| Operating Junction Temperature | T_J | -55 to +175 | °C |
| Unclamped Inductive Switching Energy (10 mH Inductor, Non-repetitive) | E_{AS} | 75 | mJ |
| ESD Rating (Human Body Model) | | 3B | |
| ESD Rating (Machine Model) | | M4 | |

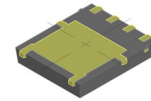
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

NOTE: The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dPD/dT_J < 1/RJA$

SCHOTTKY BARRIER RECTIFIERS 8 AMPERES 100 VOLTS



SO-8 FLAT LEAD
CASE 488AA
STYLE 2



(FULL-CUT SO8FL WF)
CASE 507BA
DFNW5

MARKING DIAGRAM



B8H100 = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-------------------|----------------------|-----------------------|
| MBR8H100MFST1G | SO-8 FL (Pb-Free) | 1500 / Tape & Reel |
| NRVB8H100MFSWFT1G | SO-8 FL (Pb-Free) | 1500 / Tape & Reel |
| NRVB8H100MFSWFT3G | SO-8 FL (Pb-Free) | 5000 / Tape & Reel |

DISCONTINUED (Note 1)

| | | |
|-----------------|----------------------|-----------------------|
| MBR8H100MFST3G | SO-8 FL (Pb-Free) | 5000 / Tape & Reel |
| NRVB8H100MFST1G | SO-8 FL (Pb-Free) | 1500 / Tape & Reel |
| NRVB8H100MFST3G | SO-8 FL (Pb-Free) | 5000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

1. **DISCONTINUED:** These devices are not recommended for new design. Please contact your onsemi representative for information. The most current information on these devices may be available on www.onsemi.com.

MBR8H100MFS, NRVB8H100MFS

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Typ | Max | Unit |
|--|-----------------|-----|------|------|
| Thermal Resistance, Junction-to-Case, Steady State (Assumes 600 mm ² 1 oz. copper bond pad, on a FR4 board) (Note 2) | $R_{\theta JC}$ | - | 2.2 | °C/W |
| Thermal Resistance, Junction-to-Ambient, Steady State (Note 2) | $R_{\theta JA}$ | - | 53.1 | °C/W |

ELECTRICAL CHARACTERISTICS

| | | | | |
|---|-------|--------------|--------------|---------------|
| Instantaneous Forward Voltage (Note 1) ($i_F = 8$ Amps, $T_J = 125^\circ\text{C}$) ($i_F = 8$ Amps, $T_J = 25^\circ\text{C}$) | V_F | 0.68 0.81 | 0.76 0.90 | V |
| Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_J = 125^\circ\text{C}$) (Rated dc Voltage, $T_J = 25^\circ\text{C}$) | i_R | 180 0.06 | 300 2 | μA |

1. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.
2. Surface-mounted on FR4 board using a 650 mm², 1 oz. Cu pad.

TYPICAL CHARACTERISTICS

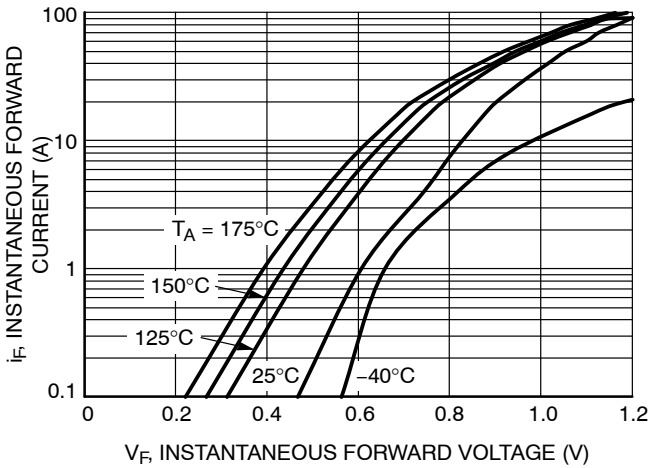


Figure 1. Typical Instantaneous Forward Characteristics

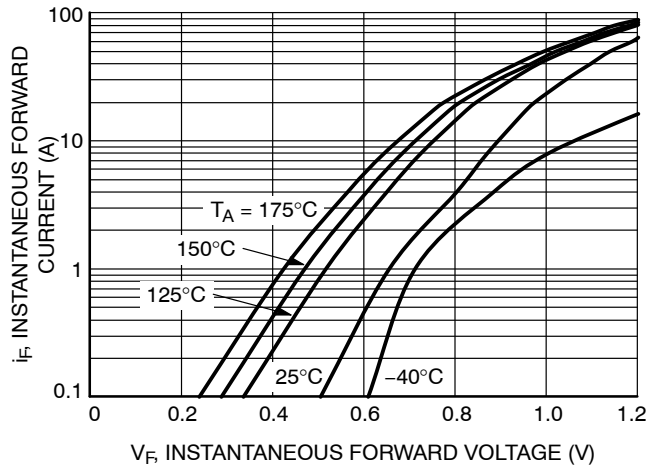


Figure 2. Maximum Instantaneous Forward Characteristics

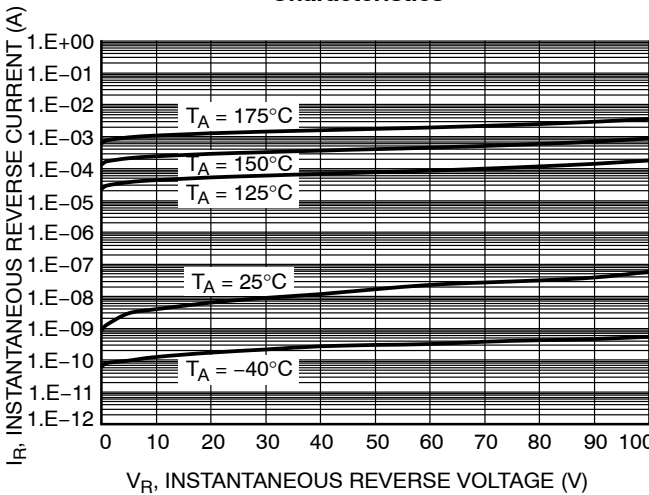


Figure 3. Typical Reverse Characteristics

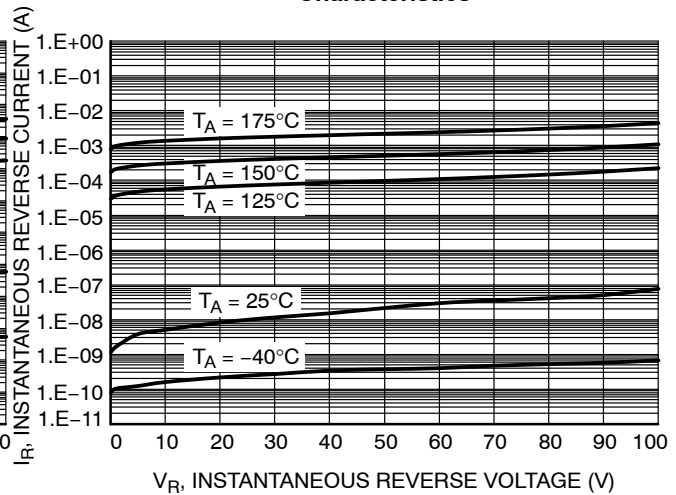


Figure 4. Maximum Reverse Characteristics

MBR8H100MFS, NRVB8H100MFS

TYPICAL CHARACTERISTICS

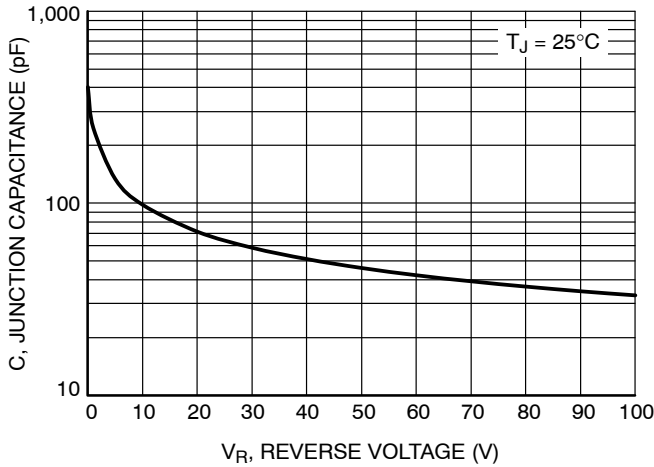


Figure 5. Typical Junction Capacitance

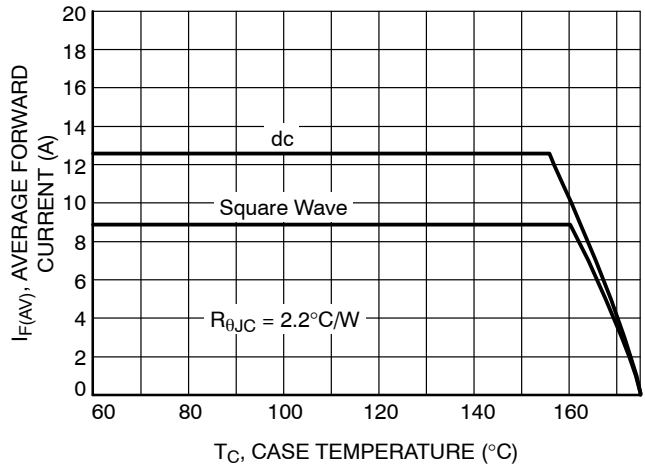


Figure 6. Current Derating

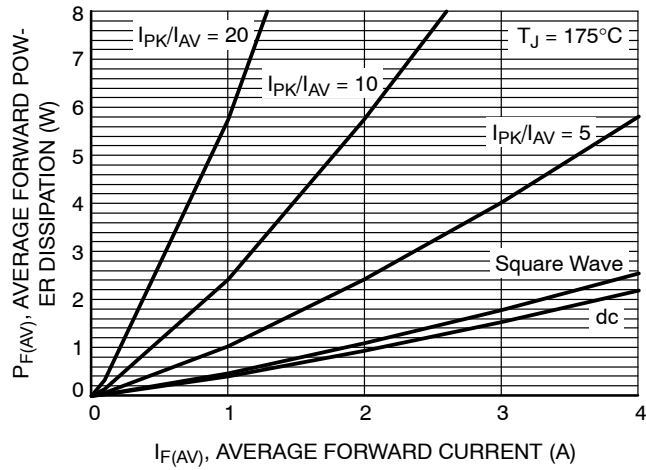


Figure 7. Forward Power Dissipation

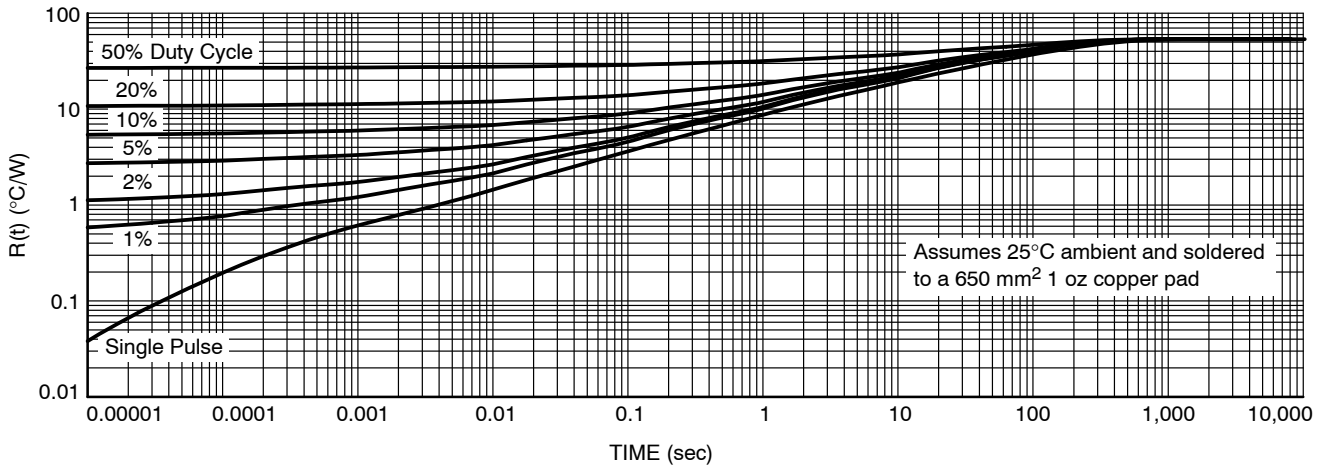
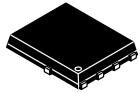


Figure 8. Thermal Response

MECHANICAL CASE OUTLINE

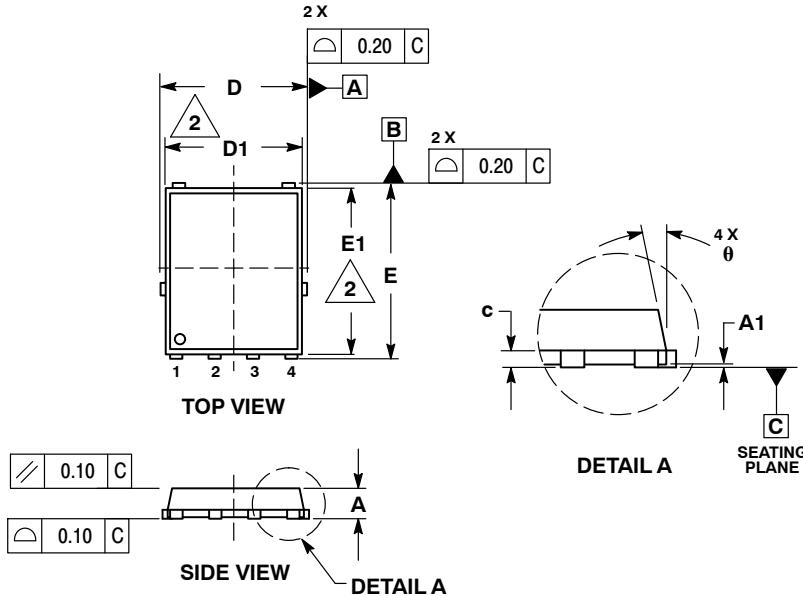
PACKAGE DIMENSIONS



1
SCALE 2:1

DFN5 5x6, 1.27P
(SO-8FL)
CASE 488AA
ISSUE N

DATE 25 JUN 2018

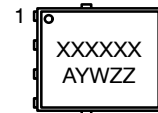


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

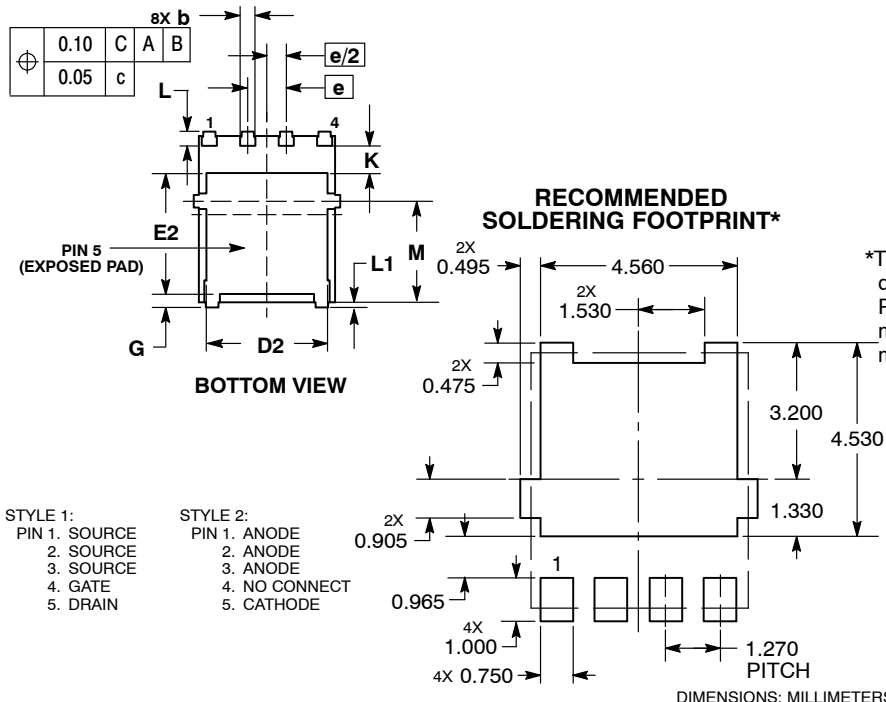
| DIM | MILLIMETERS | | |
|-----|-------------|-------|------|
| | MIN | NOM | MAX |
| A | 0.90 | 1.00 | 1.10 |
| A1 | 0.00 | --- | 0.05 |
| b | 0.33 | 0.41 | 0.51 |
| c | 0.23 | 0.28 | 0.33 |
| D | 5.00 | 5.15 | 5.30 |
| D1 | 4.70 | 4.90 | 5.10 |
| D2 | 3.80 | 4.00 | 4.20 |
| E | 6.00 | 6.15 | 6.30 |
| E1 | 5.70 | 5.90 | 6.10 |
| E2 | 3.45 | 3.65 | 3.85 |
| e | 1.27 BSC | | |
| G | 0.51 | 0.575 | 0.71 |
| K | 1.20 | 1.35 | 1.50 |
| L | 0.51 | 0.575 | 0.71 |
| L1 | 0.125 REF | | |
| M | 3.00 | 3.40 | 3.80 |
| θ | 0° | --- | 12° |

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- W = Work Week
- ZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



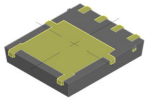
- STYLE 1:
PIN 1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
- STYLE 2:
PIN 1. ANODE
2. ANODE
3. ANODE
4. NO CONNECT
5. CATHODE

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| DESCRIPTION: | DFN5 5x6, 1.27P (SO-8FL) | PAGE 1 OF 1 |

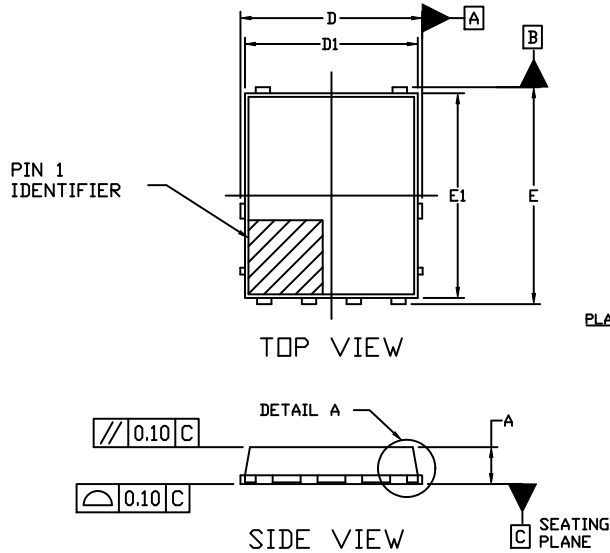
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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

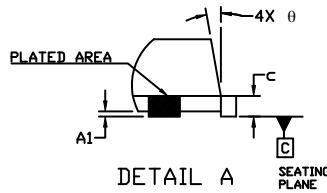


DFNW5 5x6 (FULL-CUT SO8FL WF) CASE 507BA ISSUE A

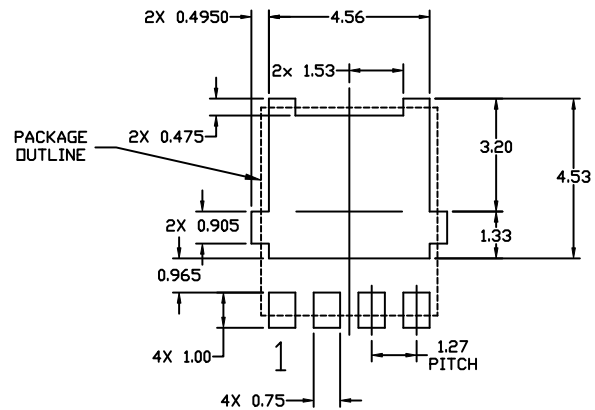
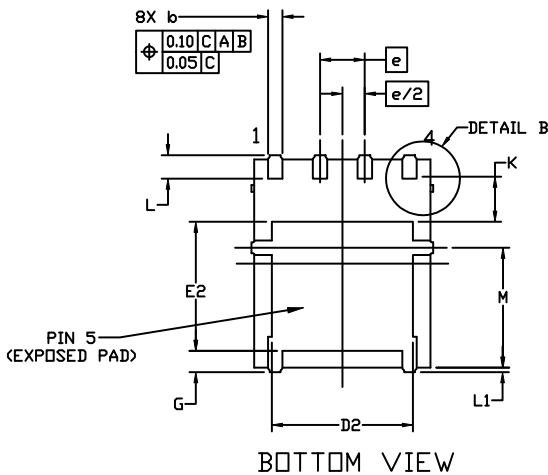
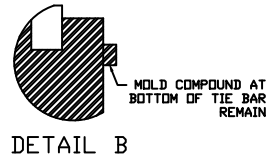
DATE 03 FEB 2021



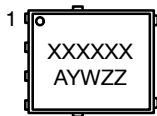
- NOTES:
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 2. CONTROLLING DIMENSION: MILLIMETERS
 3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
 4. THIS PACKAGE CONTAINS WETTABLE FLANK DESIGN FEATURES TO AID IN FILLET FORMATION ON THE LEADS DURING MOUNTING.



| DIM | MILLIMETERS | | |
|-----|-------------|-------|------|
| | MIN. | NOM. | MAX. |
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RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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